PRODUCT CHANGE NOTICE				
PART NUMBER(S):	PCN No.: 06-0130-39			
Please see attachment.	DATE: January 30, 2006			
PART DESCRIPTION:				
Power Management and Interface Products – Change in Wafer Fabrication Site				
LEVEL OF CHANGE:				
[X] Level I, Customer Approval. [] Level II, Customer Information.				
PRODUCT ATTRIBUTE AFFECTED:				
[] Material Change [] Design Change [X] Process Change	[] Data Sheet Change[] Package Change[] Packing / Shipping			
[X] Other, Explain: Wafer Fabrication Site Transfer				
DESCRIPTION OF CHANGE:				
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry Silan. See attached Product List no. 39.				
REASON FOR CHANGE:				
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.				
FABRICATION PROCESS QUALIFICATION COMPLETED (DATE): October 15, 2006 PRODUCT CHARACTERIZATION COMPLETED AND SAMPLES* AVAILABLE (DATE): October 15, 2006				

^{*} Samples representative of product from the Product Family being transferred.



Colpa	PRODUCT CHANGE NOTICE				
EARLIEST DATE O					
EFFECTIVITY CHA	NGE DATE OR DATE CODE	: Work week associated wit	th earliest production shipment.		
[] STANDARD I	DISTRIBUTION	[X]	CUSTOM DISTRIBUTION		
PERSON TO CONT	ACT WITH QUESTIONS:				
Fred Claussen					
VP Quality Assuran Sipex Corporation Phone Number: 408 FAX NUMBER: 408	3-935-7644				



PRODUCT CHANGE NOTICE

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List 39

SP6121EN SP6121EN-L SP6121CN SP6121CN-L